

# MOSFET - Power, Single N-Channel, SO8-FL 40 V, 0.42 mΩ, 509 A

## NTMFS0D4N04XM

### Features

- Low  $R_{DS(on)}$  to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- Small Footprint (5x6 mm) with Compact Design
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### Applications

- Motor Drive
- Battery Protection
- ORing

### MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise stated)

| Parameter                                                         |                                                               | Symbol         | Value       | Unit               |
|-------------------------------------------------------------------|---------------------------------------------------------------|----------------|-------------|--------------------|
| Drain-to-Source Voltage                                           |                                                               | $V_{DSS}$      | 40          | V                  |
| Gate-to-Source Voltage                                            | DC                                                            | $V_{GS}$       | $\pm 20$    | V                  |
| Continuous Drain Current                                          | $T_C = 25^{\circ}\text{C}$                                    | $I_D$          | 509         | A                  |
|                                                                   | $T_C = 100^{\circ}\text{C}$                                   |                | 360         |                    |
| Power Dissipation                                                 | $T_C = 25^{\circ}\text{C}$                                    | $P_D$          | 197         | W                  |
| Pulsed Drain Current                                              | $T_C = 25^{\circ}\text{C}$ ,<br>$t_p = 10\text{ }\mu\text{s}$ | $I_{DM}$       | 4044        | A                  |
| Operating Junction and Storage Temperature Range                  |                                                               | $T_J, T_{STG}$ | -55 to +175 | $^{\circ}\text{C}$ |
| Source Current (Body Diode)                                       |                                                               | $I_S$          | 202         | A                  |
| Single Pulse Avalanche Energy                                     | $I_{PK} = 38.6\text{ A}$                                      | $E_{AS}$       | 2396        | mJ                 |
| Lead Temperature for Soldering Purposes (1/8" from case for 10 s) |                                                               | $T_L$          | 260         | $^{\circ}\text{C}$ |

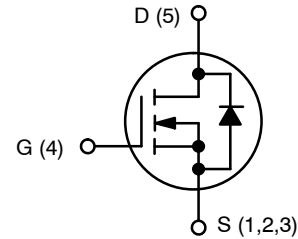
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

### THERMAL CHARACTERISTICS

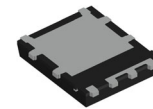
| Parameter                                            | Symbol          | Value | Unit               |
|------------------------------------------------------|-----------------|-------|--------------------|
| Thermal Resistance, Junction-to-Case (Note 2)        | $R_{\theta JC}$ | 0.76  | $^\circ\text{C/W}$ |
| Thermal Resistance, Junction-to-Ambient (Notes 1, 2) | $R_{\theta JA}$ | 38.2  |                    |

1. Surface-mounted on FR4 board using 650 mm<sup>2</sup>, 2 oz Cu pad.
2. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

| $V_{(BR)DSS}$ | $R_{DS(on)} \text{ MAX}$ | $I_D \text{ MAX}$ |
|---------------|--------------------------|-------------------|
| 40 V          | 0.42 mΩ @ 10 V           | 509 A             |

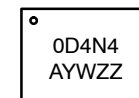


N-CHANNEL MOSFET



DFN5 (SO8-FL)  
CASE 506FA

### MARKING DIAGRAM



0D4N4 = Specific Device Code  
A = Assembly Location  
Y = Year  
W = Work Week  
ZZ = Lot Traceability

### ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 2 of this data sheet.

# NTMFS0D4N04XM

## ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25°C unless otherwise specified)

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|-----------|--------|----------------|-----|-----|-----|------|
|-----------|--------|----------------|-----|-----|-----|------|

### OFF CHARACTERISTICS

|                                                           |                                        |                                                                       |    |      |     |       |
|-----------------------------------------------------------|----------------------------------------|-----------------------------------------------------------------------|----|------|-----|-------|
| Drain-to-Source Breakdown Voltage                         | V <sub>(BR)DSS</sub>                   | V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA, T <sub>J</sub> = 25°C | 40 |      |     | V     |
| Drain-to-Source Breakdown Voltage Temperature Coefficient | ΔV <sub>(BR)DSS</sub> /ΔT <sub>J</sub> | I <sub>D</sub> = 250 μA, Referenced to 25°C                           |    | 14.9 |     | mV/°C |
| Zero Gate Voltage Drain Current                           | I <sub>DSS</sub>                       | V <sub>DS</sub> = 40 V, T <sub>J</sub> = 25°C                         |    |      | 10  | μA    |
|                                                           |                                        | V <sub>DS</sub> = 40 V, T <sub>J</sub> = 125°C                        |    |      | 100 |       |
| Gate-to-Source Leakage Current                            | I <sub>GSS</sub>                       | V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V                         |    |      | 100 | nA    |

### ON CHARACTERISTICS

|                                                |                                       |                                                                                    |     |       |      |       |
|------------------------------------------------|---------------------------------------|------------------------------------------------------------------------------------|-----|-------|------|-------|
| Drain-to-Source On Resistance                  | R <sub>DS(ON)</sub>                   | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 50 A, T <sub>J</sub> = 25°C               |     | 0.33  | 0.42 | mΩ    |
| Gate Threshold Voltage                         | V <sub>GS(TH)</sub>                   | V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 330 μA, T <sub>J</sub> = 25°C | 2.5 | 3     | 3.5  | V     |
| Gate Threshold Voltage Temperature Coefficient | ΔV <sub>GS(TH)</sub> /ΔT <sub>J</sub> | V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 330 μA                        |     | -7.21 |      | mV/°C |
| Forward Trans-conductance                      | g <sub>FS</sub>                       | V <sub>DS</sub> = 5 V, I <sub>D</sub> = 50 A                                       |     | 286   |      | S     |

### CHARGES, CAPACITANCES & GATE RESISTANCE

|                              |                     |                                                                       |  |      |  |    |
|------------------------------|---------------------|-----------------------------------------------------------------------|--|------|--|----|
| Input Capacitance            | C <sub>ISS</sub>    | V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, f = 1 MHz              |  | 8577 |  | pF |
| Output Capacitance           | C <sub>OSS</sub>    |                                                                       |  | 6090 |  |    |
| Reverse Transfer Capacitance | C <sub>RSS</sub>    |                                                                       |  | 120  |  |    |
| Output Charge                | Q <sub>OSS</sub>    | V <sub>DD</sub> = 20 V, I <sub>D</sub> = 50 A, V <sub>GS</sub> = 10 V |  | 183  |  | nC |
| Total Gate Charge            | Q <sub>G(TOT)</sub> |                                                                       |  | 133  |  |    |
| Threshold Gate Charge        | Q <sub>G(TH)</sub>  |                                                                       |  | 25.2 |  |    |
| Gate-to-Source Charge        | Q <sub>GS</sub>     |                                                                       |  | 37.2 |  |    |
| Gate-to-Drain Charge         | Q <sub>GD</sub>     |                                                                       |  | 24.2 |  |    |
| Gate Resistance              | R <sub>G</sub>      | f = 1 MHz                                                             |  | 0.42 |  | Ω  |

### SWITCHING CHARACTERISTICS

|                     |                     |                                                                                                               |  |      |  |    |
|---------------------|---------------------|---------------------------------------------------------------------------------------------------------------|--|------|--|----|
| Turn-On Delay Time  | t <sub>d(ON)</sub>  | Resistive Load, V <sub>GS</sub> = 0/10 V, V <sub>DD</sub> = 20 V, I <sub>D</sub> = 50 A, R <sub>G</sub> = 0 Ω |  | 34.5 |  | ns |
| Rise Time           | t <sub>r</sub>      |                                                                                                               |  | 11.1 |  |    |
| Turn-Off Delay Time | t <sub>d(OFF)</sub> |                                                                                                               |  | 49.4 |  |    |
| Fall Time           | t <sub>f</sub>      |                                                                                                               |  | 13   |  |    |

### SOURCE-TO-DRAIN DIODE CHARACTERISTICS

|                         |                 |                                                                                        |  |      |     |    |
|-------------------------|-----------------|----------------------------------------------------------------------------------------|--|------|-----|----|
| Forward Diode Voltage   | V <sub>SD</sub> | I <sub>S</sub> = 50 A, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 25°C                    |  | 0.79 | 1.2 | V  |
|                         |                 | I <sub>S</sub> = 50 A, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125°C                   |  | 0.63 |     |    |
| Reverse Recovery Time   | t <sub>RR</sub> | V <sub>GS</sub> = 0 V, I <sub>S</sub> = 50 A, dI/dt = 100 A/μs, V <sub>DD</sub> = 20 V |  | 94.4 |     | ns |
| Charge Time             | t <sub>a</sub>  |                                                                                        |  | 55.3 |     |    |
| Discharge Time          | t <sub>b</sub>  |                                                                                        |  | 39.1 |     |    |
| Reverse Recovery Charge | Q <sub>RR</sub> |                                                                                        |  | 316  |     | nC |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

### DEVICE ORDERING INFORMATION

| Device           | Marking | Package           | Shipping†          |
|------------------|---------|-------------------|--------------------|
| NTMFS0D4N04XMT1G | 0D4N4   | DFN5<br>(Pb-Free) | 1500 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# NTMFS0D4N04XM

## TYPICAL CHARACTERISTICS

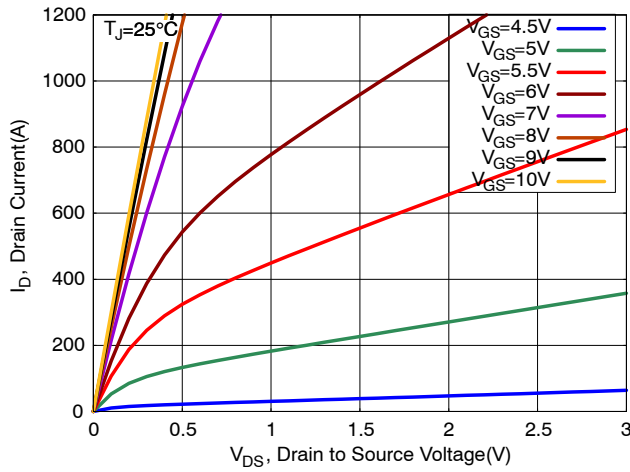


Figure 1. On-Region Characteristics

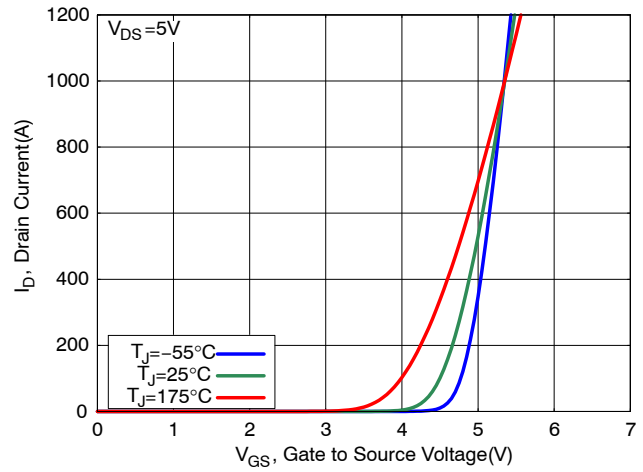


Figure 2. Transfer Characteristics

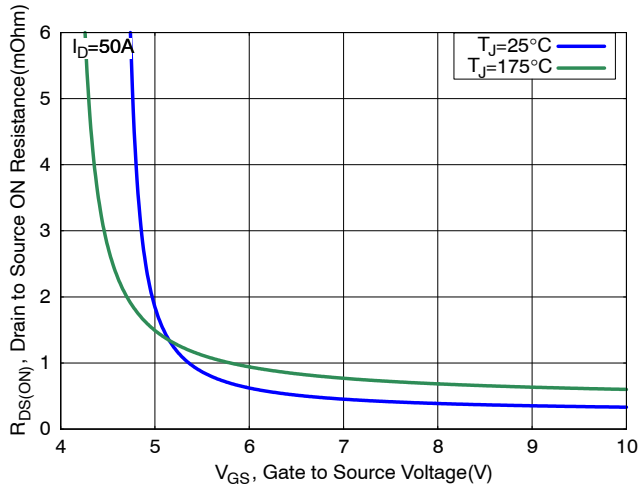


Figure 3. On-Resistance vs. Gate Voltage

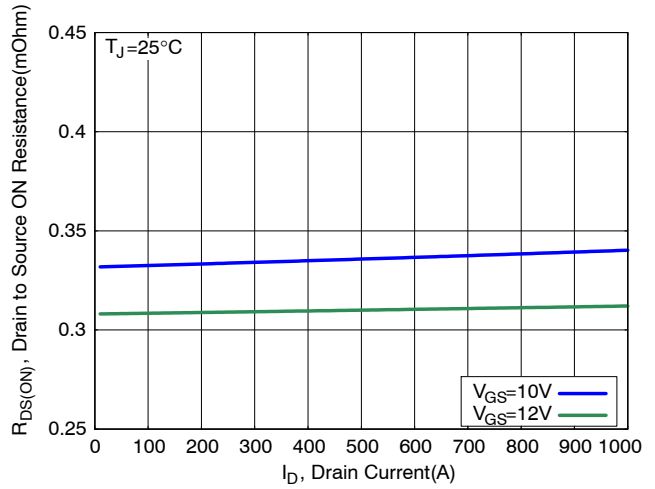


Figure 4. On-Resistance vs. Drain Current

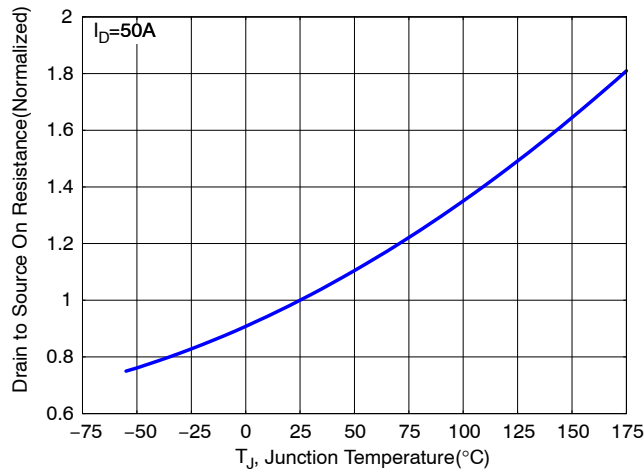


Figure 5. Normalized ON Resistance vs. Junction Temperature

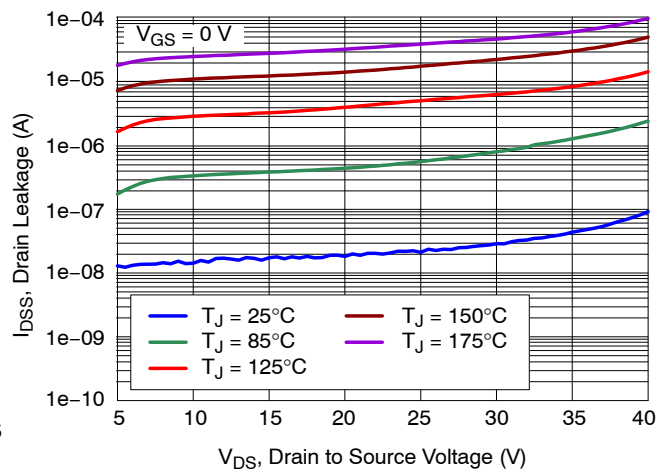


Figure 6. Drain to Source Voltage vs Drain Leakage

TYPICAL CHARACTERISTICS (CONTINUED)

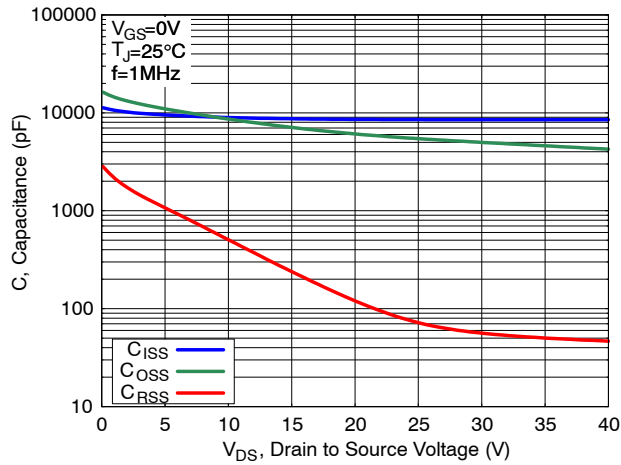


Figure 7. Capacitance Characteristics

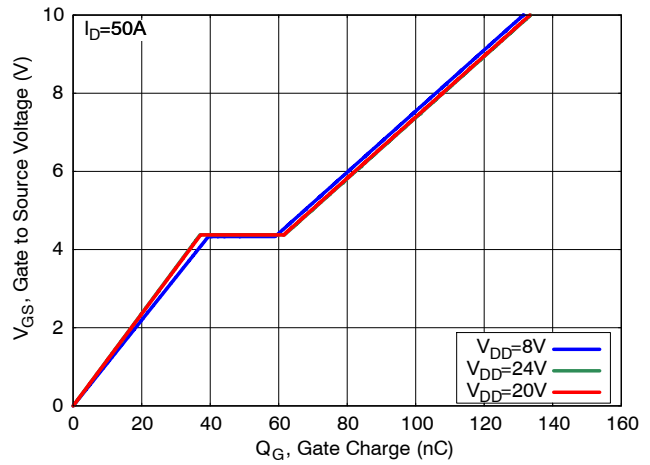


Figure 8. Gate Charge Characteristics

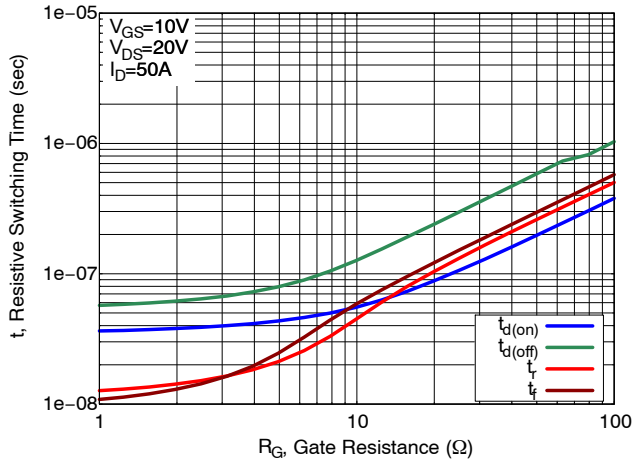


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

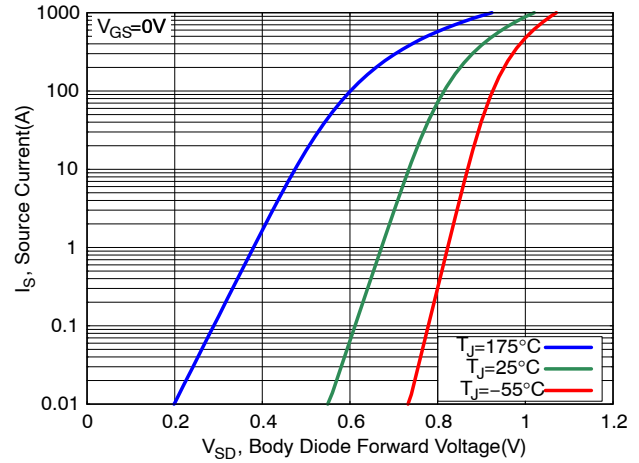


Figure 10. Diode Forward Characteristics

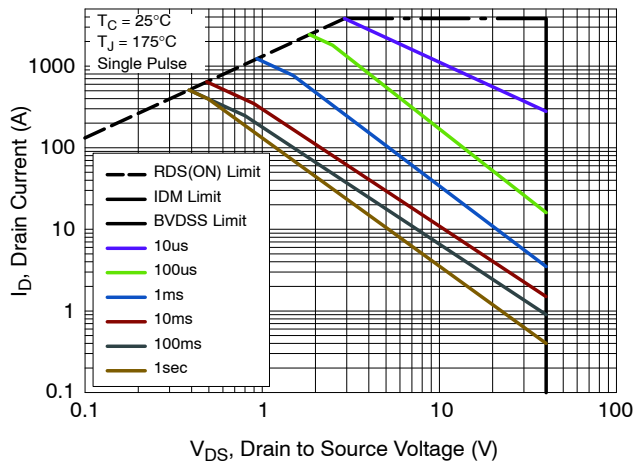


Figure 11. Safe Operating Area (SOA)

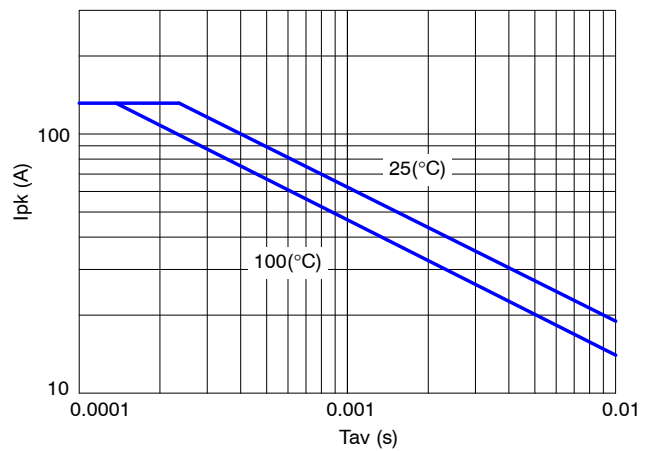


Figure 12. Avalanche Current vs. Pulse Time (UIS)

# NTMFS0D4N04XM

## TYPICAL CHARACTERISTICS (CONTINUED)

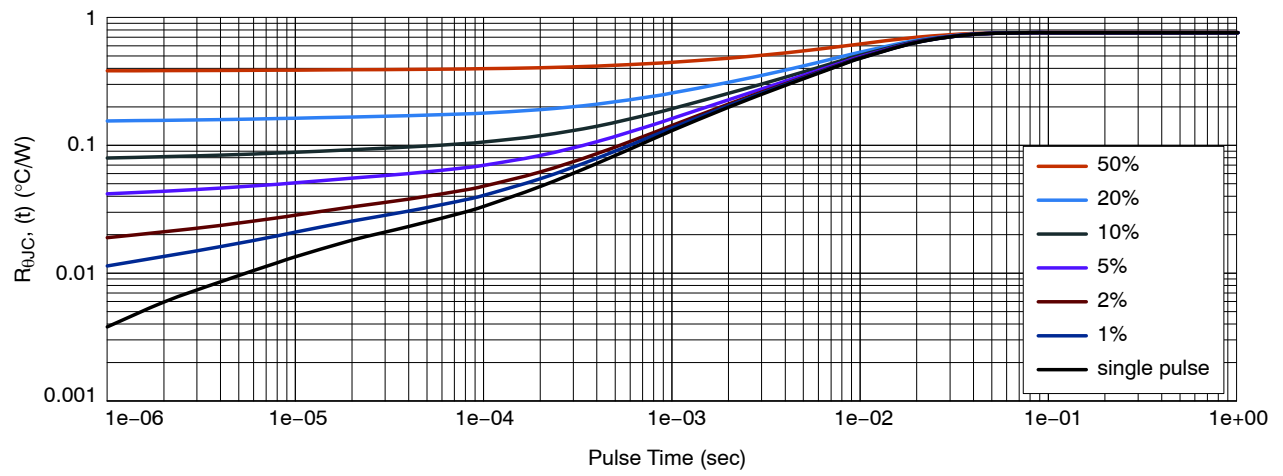
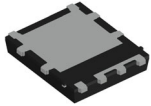
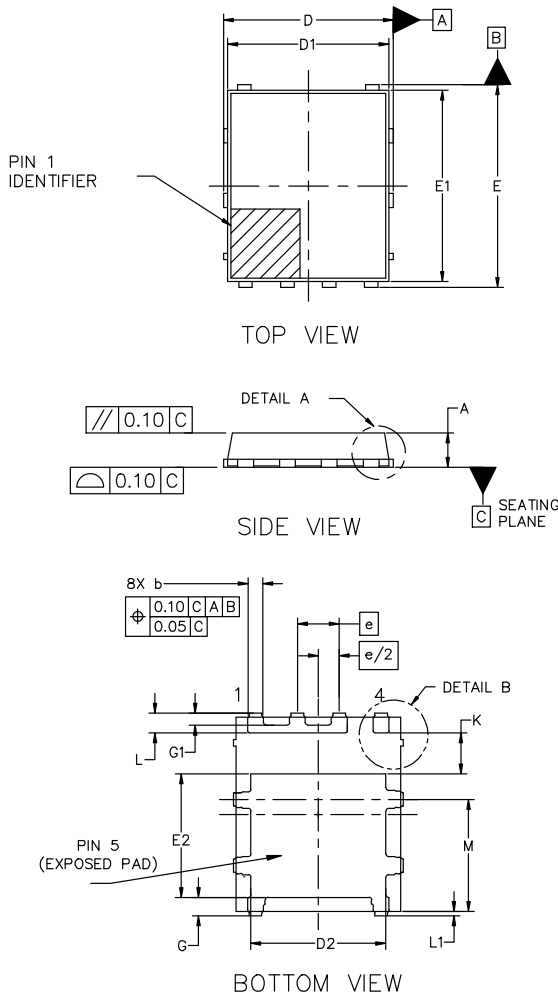


Figure 13. Thermal Response



DFN5 5.00x5.90x1.00, 1.27P  
CASE 506FA  
ISSUE A

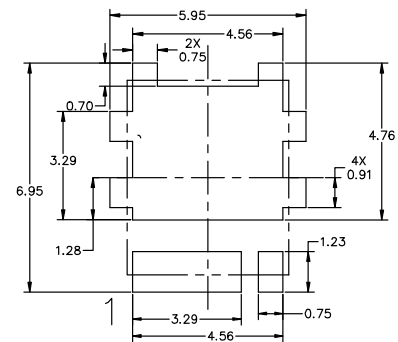
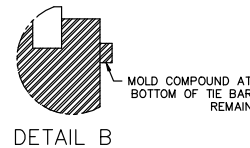
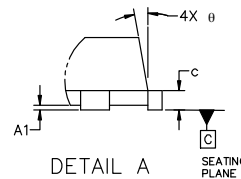
DATE 03 OCT 2024



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

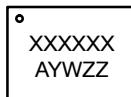
| MILLIMETERS |           |      |      |
|-------------|-----------|------|------|
| DIM         | MIN       | NOM  | MAX  |
| A           | 0.90      | 1.00 | 1.10 |
| A1          | 0.00      | ---  | 0.05 |
| b           | 0.33      | 0.41 | 0.51 |
| c           | 0.23      | 0.28 | 0.33 |
| D           | 5.00      | 5.15 | 5.30 |
| D1          | 4.80      | 5.00 | 5.20 |
| D2          | 3.90      | 4.10 | 4.30 |
| E           | 6.00      | 6.15 | 6.30 |
| E1          | 5.70      | 5.90 | 6.10 |
| E2          | 3.55      | 3.75 | 3.95 |
| e           | 1.27 BSC  |      |      |
| G           | 0.50      | 0.55 | 0.70 |
| G1          | 0.26      | 0.36 | 0.46 |
| k           | 1.10      | 1.25 | 1.40 |
| L           | 0.50      | 0.60 | 0.70 |
| L1          | 0.150 REF |      |      |
| M           | 3.00      | 3.40 | 3.80 |
| θ           | 0°        | ---  | 12°  |



RECOMMENDED MOUNTING FOOTPRINT

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC  
MARKING DIAGRAM\*



XXXX = Specific Device Code  
A = Assembly Location  
Y = Year  
W = Work Week  
ZZ = Assembly Lot Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

|                  |                            |                                                                                                                                                                                  |
|------------------|----------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
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| DESCRIPTION:     | DFN5 5.00x5.90x1.00, 1.27P | PAGE 1 OF 1                                                                                                                                                                      |

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